

Title (en)  
METALLIC MATERIAL FOR ELECTRONIC COMPONENT, METHOD FOR MANUFACTURING SAID METALLIC MATERIAL, AND CONNECTOR  
TERMINAL, CONNECTOR, AND ELECTRONIC COMPONENT IN WHICH SAID METALLIC MATERIAL IS USED

Title (de)  
METALLSTOFF FÜR ELEKTRONISCHE KOMPONENTE, VERFAHREN ZUR HERSTELLUNG DES BESAGTEN METALLSTOFFS UND  
ANSCHLUSSKLEMME, STECKVERBINDER UND ELEKTRONISCHE KOMPONENTE, IN DER DER BESAGTE METALLSTOFF VERWENDET  
WIRD

Title (fr)  
MATÉRIAU MÉTALLIQUE POUR COMPOSANT ÉLECTRONIQUE, PROCÉDÉ DE FABRICATION DUDIT MATÉRIAU MÉTALLIQUE, ET BORNE  
DE CONNECTEUR, CONNECTEUR ET COMPOSANT ÉLECTRONIQUE DANS LESQUELS LEDIT MATÉRIAU MÉTALLIQUE EST UTILISÉ

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Application  
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Abstract (en)  
The present invention provides a metallic material for electronic components having a low adhesive wear. The metallic material for electronic components comprises a base material, on the base material, a lower layer constituted with one or two or more selected from a constituent element group A consisting of Ni, Cr, Mn, Fe, Co and Cu, on the lower layer, an intermediate layer, on the intermediate layer, an upper layer constituted with an alloy comprising one or two selected from a constituent element group B consisting of Sn and In and one or two or more selected from a constituent element group C consisting of Ag, Au, Pt, Pd, Ru, Rh, Os and Ir, and on the upper layer, a treated layer having C content being 60at% or more and O content being 30at% or less. The intermediate layer consists of one or two or more selected from the constituent element group A and one or two selected from the constituent element group B, and when the metallic material is heated at 250 °C for 30 seconds, an area ratio of oxide particles adhering to a surface of the treated layer is 0.1 % or less.

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